

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Meng-Tse Chen	05/23/2011
Wei-Hung Lin	05/23/2011
Sheng-Yu Wu	05/23/2011
Chun-Cheng Lin	05/23/2011
Kuei-Wei Huang	05/23/2011
Yu-Peng Tsai	05/23/2011
Chih-Wei Lin	05/23/2011
Wen-Hsiung Lu	05/23/2011
Hsiu-Jen Lin	05/23/2011
Bor-Ping Jang	05/23/2011
Ming-Da Cheng	05/23/2011
Chung-Shi Liu	05/23/2011

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77 R.O.C.

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13118108

CORRESPONDENCE DATA

Fax Number: (972)732-9218
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
 Phone: 972-732-1001

CH \$40.00 13118108

501547852

PATENT
REEL: 026356 FRAME: 0947

Email: edwards@slater-matsil.com
Correspondent Name: Slater & Matsil, L.L.P.
Address Line 1: 17950 Preston Road
Address Line 2: Suite 1000
Address Line 4: Dallas, TEXAS 75252

ATTORNEY DOCKET NUMBER:

TSM11-0165

NAME OF SUBMITTER:

Kasey Edwards

Total Attachments: 3

source=TSM11-0165_Assignment#page1.tif

source=TSM11-0165_Assignment#page2.tif

source=TSM11-0165_Assignment#page3.tif

ATTORNEY DOCKET NO.
TSM11-0165

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Package-on-Package Process for Applying Molding Compound			
SIGNATURE OF INVENTOR AND NAME	<i>Chen, Meng-Tse</i> Meng-TseChen	<i>Wei-Hung Lin</i> Wei-HungLin	<i>Sheng-Yu Wu</i> Sheng-YuWu	<i>Chun-Cheng Lin</i> Chun-ChengLin
DATE	2011/05/23	2011/05/23	2011/5/23	2011.5.23
RESIDENCE (City, County, State)	Changzhi Township, Taiwan	Xinfeng Township, Taiwan	Hsin-Chu, Taiwan	New Taipei City, Taiwan

ATTORNEY DOCKET NO.
TSM11-0165

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

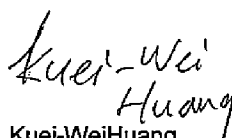
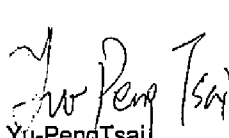
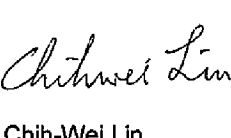
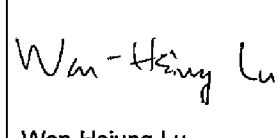
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Package-on-Package Process for Applying Molding Compound</i>			
SIGNATURE OF INVENTOR AND NAME	 Kuei-Wei Huang	 Yu-Peng Tsai	 Chih-Wei Lin	 Wen-Hsiung Lu
DATE	2011. 5/23	2011. 5.23	2011. 5/23	2011 05/23
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan	Taipei City, Taiwan	Xinfeng Township, Taiwan	Jhonghe City, Taiwan

ATTORNEY DOCKET NO.
TSM11-0165

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Package-on-Package Process for Applying Molding Compound</i>			
SIGNATURE OF INVENTOR AND NAME	<i>Hsiu-Jen Lin</i> Hsiu-Jen Lin	<i>Bor-Ping Jang</i> Bor-Ping Jang	<i>Ming-Da Cheng</i> Ming-Da Cheng	<i>Chung-Shi Liu</i> Chung-Shi Liu
DATE	2011 05/23	2011 05/23	2011 05/23	2011 / 5 / 23
RESIDENCE (City, County, State)	Zhubei City, Taiwan	Chu-Bei, Taiwan	Jhubei City, Taiwan	Hsin-Chu, Taiwan